

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT5905124

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
AKITO KURAMATA	11/29/2019
SHINYA WATANABE	11/29/2019
KOHEI SASAKI	12/06/2019
KUNIAKI YAGI	12/16/2019
NAOKI HATTA	12/18/2019
MASATAKA HIGASHIWAKI	11/28/2018
KEITA KONISHI	11/29/2019
RECEIVING PARTY DATA	
Name:	TAMURA CORPORATION
Street Address:	1-19-43, HIGASHI-OIZUMI, NERIMA-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	178-8511
Name:	SICOXS CORPORATION
Street Address:	SHIMBASHI SUMITOMO BUILDING 7F
Internal Address:	5-11-3 SHIMBASHI, MINATO-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	105-0004
Name:	NATIONAL INSTITUTE OF INFORMATION AND COMMUNICATIONS TECHNOLOGY
Street Address:	4-2-1, NUKUI-KITAMACHI, KOGANEI-SHI
City:	TOKYO
State/Country:	JAPAN
Postal Code:	184-8795
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16630087
CORRESPONDENCE DATA	
PATENT	

Fax Number: (516)742-4366

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 516-742-4343

Email: jmoses@ssmp.com

Correspondent Name: SCULLY SCOTT MURPHY & PRESSER, PC

Address Line 1: 400 GARDEN CITY PLAZA

Address Line 2: SUITE 300

Address Line 4: GARDEN CITY, NEW YORK 11530

ATTORNEY DOCKET NUMBER:	38038
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NAME OF SUBMITTER:	PAUL J. ESATTO, JR.
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SIGNATURE:	/Paul J. Esatto, Jr./
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DATE SIGNED:	01/10/2020
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Total Attachments: 9

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**COMBINED DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN
APPLICATION AND ASSIGNMENT**

As a below named inventor, I hereby declare that:

This declaration ☐ the attached application, or
is directed to:

☒ United States application or PCT international application number
PCT/JP2018/025900 filed on July 9, 2018; and

entitled: SEMICONDUCTOR SUBSTRATE, SEMICONDUCTOR ELEMENT AND
METHOD FOR PRODUCING SEMICONDUCTOR SUBSTRATE

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the
application.

I hereby state that I have reviewed and understand the contents of the above-identified application,
including the claims.

I am aware of the duty to disclose to the United States Patent and Trademark Office all information
known to me to be material to patentability as defined in 37 CFR 1.56.

Whereas, the undersigned inventor(s) has/have made certain inventions, improvements and
discoveries (herein referred to as the "Invention") disclosed in the above-identified patent
application;

Whereas, TAMURA CORPORATION, a corporation of Japan, having a place of
business at 1-19-43, Higashi-Oizumi, Nerima-ku, Tokyo 178-8511, Japan and SICOXS
CORPORATION, a corporation of Japan, having a place of business at Shimbashi
Sumitomo Building 7F, 5-11-3 Shimbashi, Minato-ku, Tokyo 105-0004, Japan and NATIONAL
INSTITUTE OF INFORMATION AND COMMUNICATIONS TECHNOLOGY, a corporation
of Japan, having a place of business at 4-2-1, Nukui-Kitamachi, Koganei-shi, Tokyo,
184-8795, Japan, desires to acquire, and each undersigned inventor desires to grant to
TAMURA CORPORATION and SICOXS CORPORATION and NATIONAL
INSTITUTE OF INFORMATION AND COMMUNICATIONS TECHNOLOGY, the entire
worldwide right, title and interest in and to any and all patent applications and patents directed
thereto;

Now, therefore, in consideration of One Dollar (\$1.00), and other good and valuable
considerations, the receipt of which is hereby acknowledged, each undersigned inventor
("ASSIGNOR") hereby sells, assigns and transfers to TAMURA CORPORATION and
SICOXS CORPORATION and NATIONAL INSTITUTE OF INFORMATION AND

COMMUNICATIONS TECHNOLOGY (the "ASSIGNEE"), its successors, assigns and legal representatives, the entire right, title and interest for all countries, in and to the Invention, the above-identified United States patent application, and any and all other patent applications and patents for the Invention which may be applied for or granted therefor in the United States and in all foreign countries and jurisdictions, including all divisional, continuing, substitute, reexamination, renewal, reissue and extensions thereof, and all rights of priority resulting from the filing of such applications and granting of such patents. In addition, each undersigned inventor hereby authorizes and requests the Commissioner of Patents to issue, in accordance with this assignment, any and all United States Letters Patent, and foreign patent authorities to issue any foreign patent, granted for the Invention to said Assignee, the corporation above named, its successors, assigns and legal representatives; and agreeing to carry out in good faith the intent and purpose of this assignment, the undersigned will, for the United States and all foreign countries, execute all divisional, continuing, substitute, renewal, reissue and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee its successors, assigns and representatives, all facts known to the undersigned relating to said improvements and the history thereof; testify in all legal proceedings; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing, maintaining and enforcing proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

Legal name of sole or first inventor Akito KURAMATA	
Sole or first inventor's signature <i>Akito Kuramata</i>	Date 29, Nov., 2019

Legal name of second inventor Shinya WATANABE	
Second inventor's signature <i>Shinya Watanabe</i>	Date 29, Nov., 2019

Legal name of third inventor Kohei SASAKI	
Third inventor's signature <i>Kohei Sasaki</i>	Date 6, Dec., 2019

Legal name of fourth inventor Kuniaki YAGI	
Fourth inventor's signature	Date

Legal name of fifth inventor Naoki HATTA	
Fifth inventor's signature	Date

Legal name of sixth inventor Masataka HIGASHIWAKI	
Sixth inventor's signature	Date

Legal name of seventh inventor Keita KONISHI	
Seventh inventor's signature <i>Keita Konishi</i>	Date <i>29. Nov, 2019</i>

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inventor desires to grant to TAMURA CORPORATION and SICOXS
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COMMUNICATIONS TECHNOLOGY, the entire worldwide right, title and interest in and
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and SICOXS CORPORATION and NATIONAL INSTITUTE OF INFORMATION
AND COMMUNICATIONS TECHNOLOGY (the "ASSIGNEE"), its successors, assigns
and legal representatives, the entire right, title and interest for all countries, in and to the
Invention, the above-identified United States patent application, and any and all other patent

applications and patents for the Invention which may be applied for or granted therefor in the United States and in all foreign countries and jurisdictions, including all divisional, continuing, substitute, reexamination, renewal, reissue and extensions thereof, and all rights of priority resulting from the filing of such applications and granting of such patents. In addition, each undersigned inventor hereby authorizes and requests the Commissioner of Patents to issue, in accordance with this assignment, any and all United States Letters Patent, and foreign patent authorities to issue any foreign patent, granted for the Invention to said Assignee, the corporation above named, its successors, assigns and legal representatives; and agreeing to carry out in good faith the intent and purpose of this assignment, the undersigned will, for the United States and all foreign countries, execute all divisional, continuing, substitute, renewal, reissue and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee its successors, assigns and representatives, all facts known to the undersigned relating to said improvements and the history thereof; testify in all legal proceedings; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing, maintaining and enforcing proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

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Sole or first inventor's signature	Date

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Second inventor's signature	Date

Legal name of third inventor Kohei SASAKI	
Third inventor's signature	Date

Legal name of fourth inventor Kuniaki YAGI	
Fourth inventor's signature <i>K. Yagi</i>	Date <i>December 16, 2019</i>

Legal name of fifth inventor Naoki HATTA	
Fifth inventor's signature <i>Naoki Hatta</i>	Date <i>December 18, 2019</i>

Legal name of sixth inventor Masataka HIGASHIWAKI	
Sixth inventor's signature	Date

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Fifth inventor's signature	Date

Legal name of sixth inventor Masataka HIGASHIWAKI	
Sixth inventor's signature	Date

M. Higashiwaki Nov 28, 2019

Legal name of seventh inventor Keita KONISHI	
Seventh inventor's signature	Date